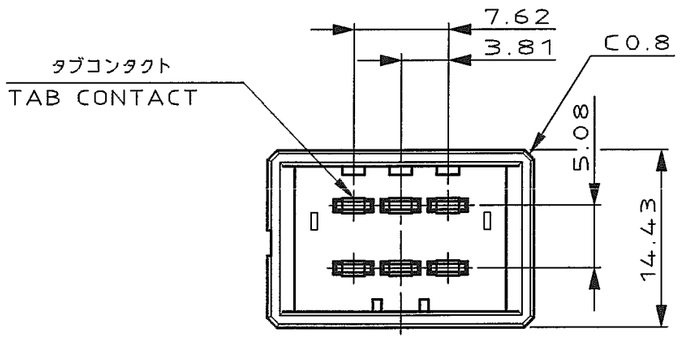
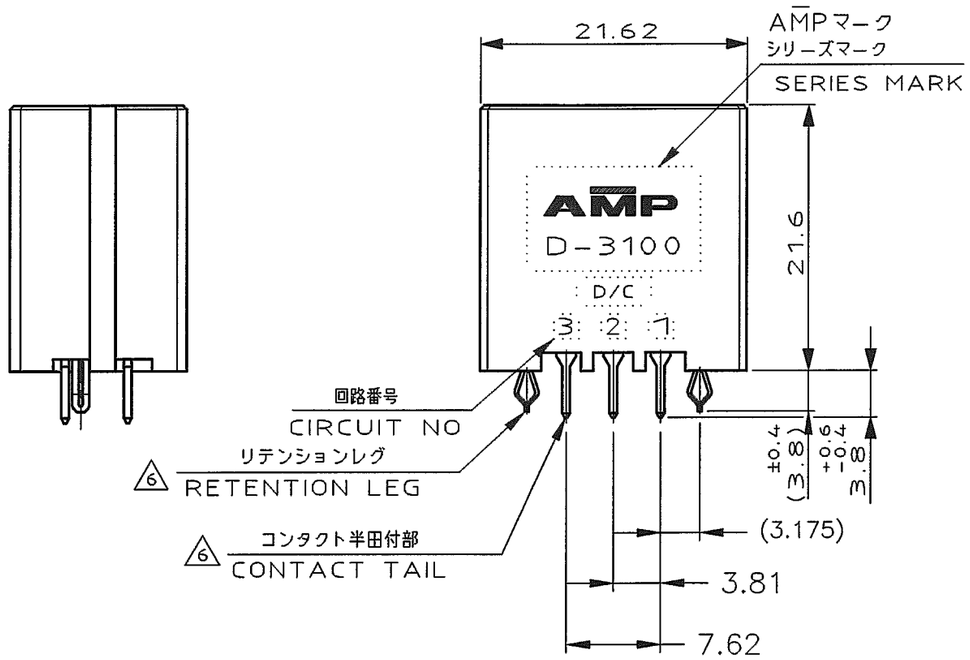
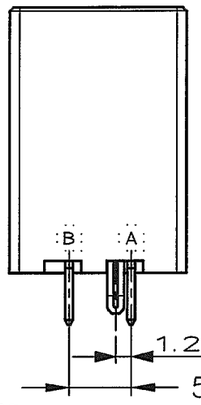
NUMBER 178323

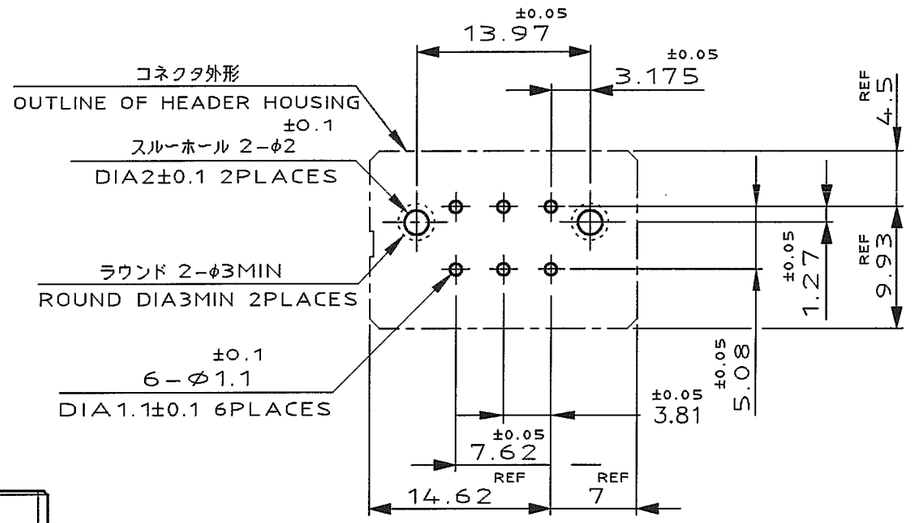
3rd ANGLE PROJECTION

METRIC









推奨基板取付け穴寸法

PC 基板厚:1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN

PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER
CONTACT:COPPER ALLOY
RETENTION LEG:COPPER ALLOY
2. FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING
3. FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING
4. FINISH(CONTACT AREA):2.0 μmMIN TIN PLATED OVER NICKEL
~~5. FINISH(RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL~~
6. FINISH(RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
2. めっき: コンタクト: 全面Ni下地 接触部:0.38μm MIN金めっき
3. めっき: コンタクト: 全面Ni下地 接触部:0.76μm MIN金めっき
4. めっき: コンタクト: 全面Ni下地 接触部:2.0 μm MINスズめっき
~~5. めっき: リテンションレグとコンタクト半田付部 : ニッケル下地の上に半田めっき~~
6. めっき リテンションレグとコンタクト半田付部 : ニッケル下地の上にスズめっき

		製品番号 (PART NO.)
6	4	178323-5
6	3	178323-3
6	2	178323-2
(FINISH)		

LTR	REVISION RECORD		DR	CHK	DATE
D	REVISED	FJD0-0039-03	T S	S.M	6/2 '03
C	REVISED	FJD0-0097-03	TS	S.M	4/15 '03
B	REVISED	FJ00-0838-94	NM	S.M	7/4 '94
A	REDRAWN WITH CHANGE	FJ00-0480-94	NM	S.M	4/20 '94

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tyco Electronics
Tyco Electronics AMP K.K
Kawasaki,Japan

WIRE RANGE / INSULATION DIA	mm²(AWG -) / - mmφ
MATERIAL	SEE NOTE 注記参照
FINISH	SEE NOTE 注記参照
DR.	N.Matsubara 15 FEB 91
DE.	N.Matsubara 15 FEB 91
CHK.	T.Obata 21 MAY '91
APP.	S.MINABE 21-MAY-'91

NAME: DOUBLE ROW (D-3100)
DYNAMIC CONN. 6POS. VERTICAL HDR. ASS'Y

一般公差 (GENERAL TOLERANCE): 10未満 ±0.3; 10以上30未満 ±0.4; 30以上100未満 ±0.5; 角度 ±3°

SIZE	LOC	NUMBER
A3	J	C-178323

SCALE	REV.	SHEET
2-1	D	1 OF 1

(CUSTOMER DRAWING) 顧客用図面

PRINT DIST

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

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